

<b>Notification Number:</b>	20200625002	<b>Notification Date:</b>	July 22, 2020
<b>Title:</b>	Datasheet for TPS63802		
<b>Customer Contact:</b>	PCN Manager	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

**Notification Details**

**Description of Change:**

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



**TPS63802**

SLVSEU9C – NOVEMBER 2018 – REVISED JUNE 2020

Changes from Revision B (September 2019) to Revision C	Page
• Added device comparison .....	3
• Changed 1x 22 µF to 2x 22 µF.....	19
• Changed Part Number from TPS63802RMW to TPS63802DLA .....	20
• Change MODE from High to Low .....	22
• Change MODE from High to Low .....	22
• Change MODE from Low to High .....	23
• Deleted layout guideline to separate AGND and PGND .....	27
• Changed Use a common-power GND, but connect AGND and PGND through via at a different layer. to Use a common ground node for power ground and a different one for control ground to minimize the effects of ground noise. Connect these ground nodes at any place close to one of the ground pins of the IC. ....	27
• Added Related Links section .....	28

The datasheet number will be changing.

Device Family	Change From:	Change To:
TPS63802	SLVSEU9B	SLVSEU9C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TPS63802>

**Reason for Change:**

To accurately reflect device characteristics.

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

**Changes to product identification resulting from this notification:**

None.

**Product Affected:**

TPS63802DLAR	TPS63802DLAT		
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For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
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